

REV.	SPECIFICATION	ECN NO.	APPD.
X3			

**Material:**  
Housing: High Temperature Plastic UL94V-0.  
Contacts: Copper Alloy.

**Electrical Characteristics:**  
Current Rating: Power Pin 12.5A (UL).  
Signal Pin 1.5A.

**Dielectric Withstanding Voltage:**  
Power Pin DC 1000V For 1 Minute.  
Signal Pin DC 500V For 1 Minute.

**Contact Resistance:** Power Pin 0.6mΩ max.  
Signal Pin 25mΩ max.

**Insulation Resistance:** Power Pin 5000MΩ min. at DC 500V.  
Signal Pin 500MΩ min. at DC 500V.

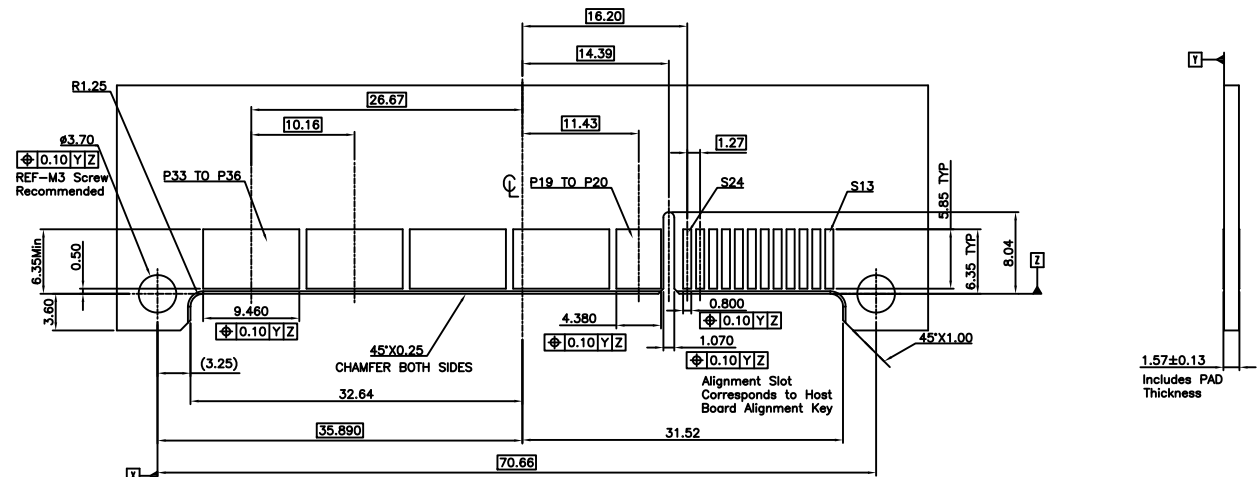
**Operating Temperature:** -55°C~+105°C.

**\*Rohs Compliant**

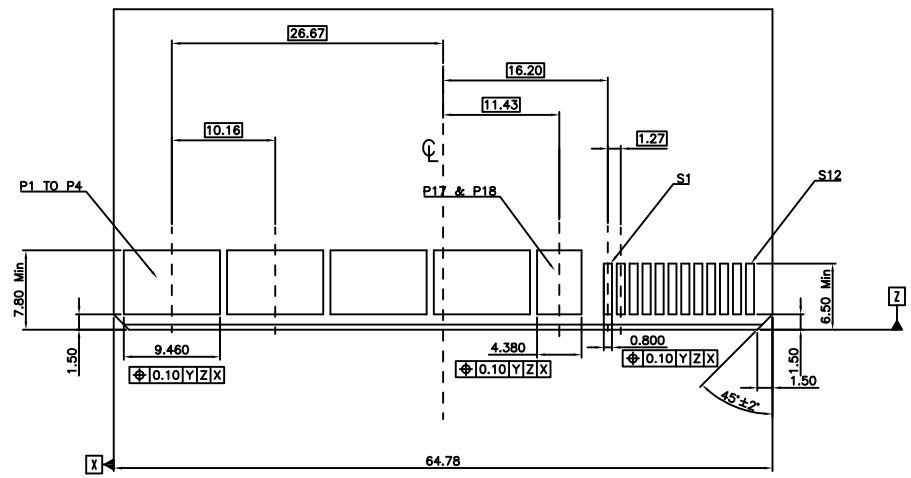
- 9302- 2 A1 S24 N 1 1 3 A CB30 K A
- Series
  - 2:Female straighty
  - Type: A1
  - A1:H16P02
  - Empty:Without Signal
  - S24:Signal Pin
  - N:W/O Post
  - 1:Begin DIM G 1.10mm
  - 1:End DIM G 1.30mm
  - 3: W/O Front Key,With Host Board Key,With Screw Holes
  - A: Tray Package
  - K:Straddle Type
  - CB30: Contact Au+Pd/Ni , Dip Tin 30u"
  - C10: Selective Gold Plated 10u"
  - A:Signal pitch 1.27
  - B:Signal pitch 2.54

Tolerances	Dwg No.	9302-D0000-009	Title:	<b>9302 Series</b> High Power And Signal Edge Card Connector	 <b>OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.</b> P/N: 9302-2A1S24N113ACB30KA				
X= ±0.5	Projection		Scale			1:1			
.X= ±0.25	Unit	mm	Drawn By			WP 08/20'15			
.XX= ±0.15									
					<table border="1"> <tr> <td>SHEET</td> <td>1/2</td> <td>Ver.No.</td> <td>X3</td> </tr> </table>	SHEET	1/2	Ver.No.	X3
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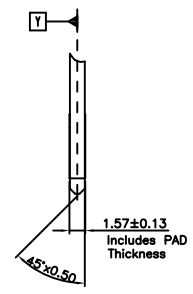
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Recommended Host Board Layout



Recommended Mating Board



Tolerances	Dwg No.	9302-D0000-009	Title:
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<b>OUPIN</b>			
OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 9302-2A1S24N113ACB30KA			
SHEET	2/2	Ver.No.	X3